

Product Summary

$V_{(BR)CES}$	$V_{CE(SAT)TYP}$	$I_C(100^\circ C)$
650V	1.60V@15V	20A

Feature

- Maximum junction temperature 175°C
- Positive temperature coefficient
- High ruggedness, temperature stable
- High speed smooth switching device for hard and soft switching

Application

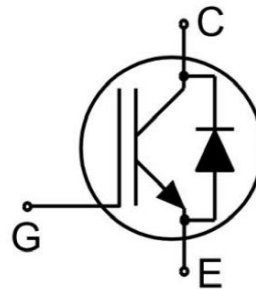
- Soft switching applications
- Air conditioning
- Motor drive inverter

Package



TO-263AB

Circuit diagram



Marking



Absolute maximum ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CES}	650	V
Continuous Gate- Emitter Voltage	V_{GE}	± 20	V
Transient Gate-Emitter Voltage ($t_p \leq 10\mu\text{s}, D < 0.01$)	V_{GE}	± 30	V
Collector Current, limited by T_{jmax}	I_C	40	A
Collector Current, limited by T_{jmax} ($T_C=100^\circ\text{C}$)	$I_C(100^\circ\text{C})$	20	A
Pulsed Collector Current, t_p limited by T_{jmax} ($V_{GE}=15\text{V}$)	I_{CM}	60	A
Diode Continuous Forward Current, limited by T_{jmax}	I_F	40	A
Diode Continuous Forward Current, limited by T_{jmax} ($T_C=100^\circ\text{C}$)	$I_F(100^\circ\text{C})$	20	A
Diode Pulsed Current, t_p limited by T_{jmax}	I_{Fpuls}	60	A
Turn off Safe Operating Area ($V_{CE} \leq 600\text{V}, T_J \leq 150^\circ\text{C}$)	-	60	A
Short Circuit Withstand Time ($V_{GE}=15\text{V}, V_{CE}=400\text{V}$)	T_{sc}	5	μs
Power Dissipation ($T_J=175^\circ\text{C}$)	P_D	120	W
Thermal Resistance, Junction to case for Diode	$R_{\theta JC}$	1.5	$^\circ\text{C/W}$
Thermal Resistance, Junction to case for IGBT	$R_{\theta JC}$	1.25	$^\circ\text{C/W}$
Operating junction temperature range	T_J	$-40 \sim +175$	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	$-55 \sim +150$	$^\circ\text{C}$

Electrical characteristics of the IGBT ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Collector-Emitter Breakdown Voltage	$V_{(BR)CES}$	$V_{GE}=0\text{V}, I_C=250\mu\text{A}$	650			V
Collector-Emitter Leakage Current	I_{CES}	$V_{GE}=0\text{V}, V_{CE}=650\text{V}$			0.25	mA
		$V_{GE}=0\text{V}, V_{CE}=650\text{V}, T_J=150^\circ\text{C}$			1	
Gate to Emitter Leakage Current	I_{GES}	$V_{GE}=\pm 20\text{V}, V_{CE}=0\text{V}$			± 200	nA
Gate Threshold Voltage	$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C=1\text{mA}$	5	5.8	6.5	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE}=15\text{V}, I_C=20\text{A}$		1.6	1.95	V
		$V_{GE}=15\text{V}, I_C=20\text{A}, T_J=125^\circ\text{C}$		1.75		
		$V_{GE}=15\text{V}, I_C=20\text{A}, T_J=150^\circ\text{C}$		1.8		
Dynamic characteristics						
Input Capacitance	C_{ies}	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		0.9		nF
Output Capacitance	C_{oes}			0.04		
Reverse Transfer Capacitance	C_{res}			0.01		
Total Gate Charge	Q_g	$V_{CC}=300\text{V}, V_{GE}=15\text{V}, I_C=20\text{A}$		0.085		μC
Turn-on delay time	$t_{d(on)}$	$V_{CC}=300\text{V}, V_{GE}=-5\text{V}\sim 15\text{V}$ $I_C=20\text{A}, R_G=51\Omega$		12		nS
Turn-on rise time	t_r			33		
Turn-off delay time	$t_{d(off)}$			68		
Turn-off fall time	t_f			129		
Turn-On Switching Loss	E_{on}				0.41	
Turn-Off Switching Loss	E_{off}			0.22		

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Dynamic characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 300V, V_{GE} = -5V \sim 15V$ $I_C = 20A, R_G = 51\Omega$ $T_J = 125^\circ C$		16		nS
Turn-on rise time	t_r			41		
Turn-off delay time	$t_{d(off)}$			69		
Turn-off fall time	t_f			154		
Turn-On Switching Loss	E_{on}			0.48		mJ
Turn-Off Switching Loss	E_{off}			0.35		
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 300V, V_{GE} = -5V \sim 15V$ $I_C = 20A, R_G = 51\Omega$ $T_J = 150^\circ C$		18		nS
Turn-on rise time	t_r			49		
Turn-off delay time	$t_{d(off)}$			69		
Turn-off fall time	t_f			173		
Turn-On Switching Loss	E_{on}			0.52		mJ
Turn-Off Switching Loss	E_{off}			0.38		

Electrical characteristics of the Diode ($T_J = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Diode Forward Voltage	V_F	$I_F = 20A$		2	2.5	V
		$I_F = 20A, T_J = 125^\circ C$		1.8		
		$I_F = 20A, T_J = 150^\circ C$		1.7		
Reverse Recovery Current	I_{rrm}	$V_R = 300V, I_F = 20A$ $di/dt = -360A/\mu s$		6		A
Reverse Recovery Charge	Q_{rr}			0.25		μC
Reverse Recovery Time	T_{rr}			200		nS
Reverse Recovery Energy	E_{rec}			0.07		mJ
Reverse Recovery Current	I_{rrm}	$V_R = 300V, I_F = 20A$ $di/dt = -360A/\mu s$ $T_J = 125^\circ C$		8		A
Reverse Recovery Charge	Q_{rr}			0.59		μC
Reverse Recovery Time	T_{rr}			218		nS
Reverse Recovery Energy	E_{rec}			0.13		mJ
Reverse Recovery Current	I_{rrm}	$V_R = 300V, I_F = 20A$ $di/dt = -360A/\mu s$ $T_J = 150^\circ C$		9		A
Reverse Recovery Charge	Q_{rr}			0.78		μC
Reverse Recovery Time	T_{rr}			227		nS
Reverse Recovery Energy	E_{rec}			0.16		mJ

Typical Characteristics

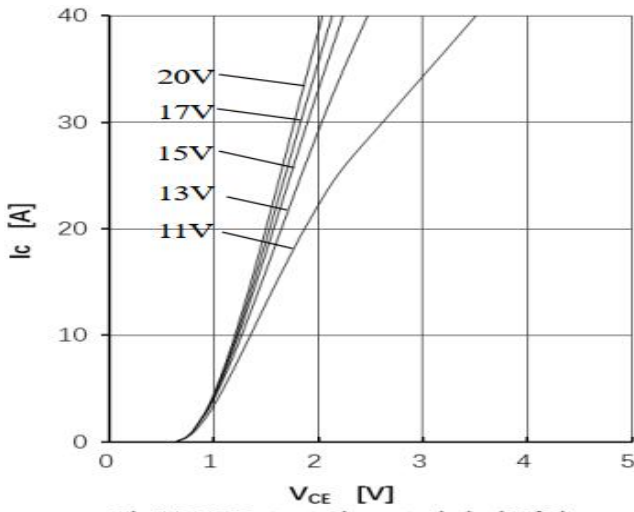


Fig1. IGBT Output Characteristics(25°C)

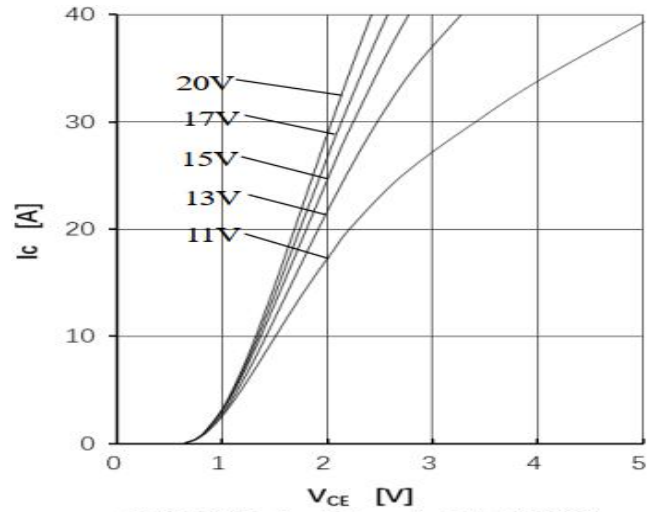


Fig2. IGBT Output Characteristics(150°C)

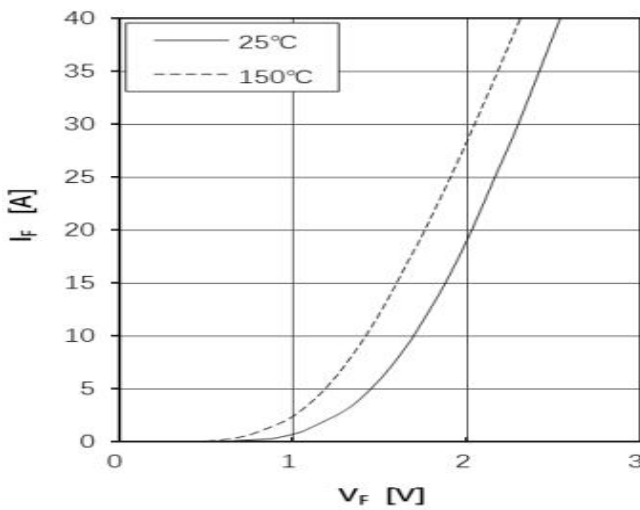


Fig3. Diode Forward Characteristics

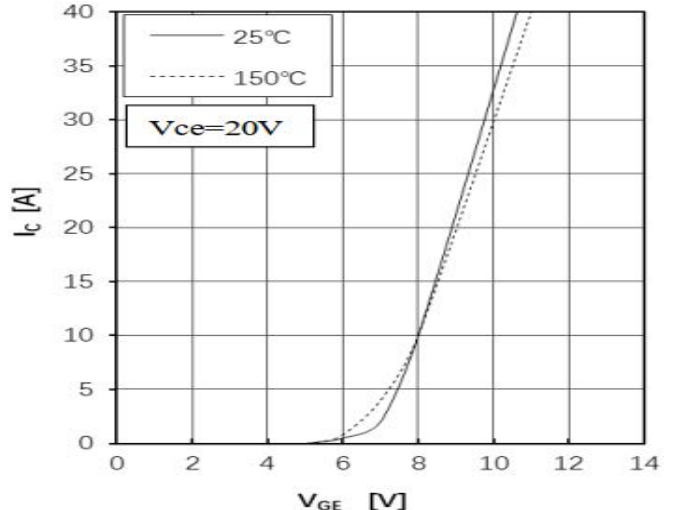


Fig4. IGBT Transfer Characteristics

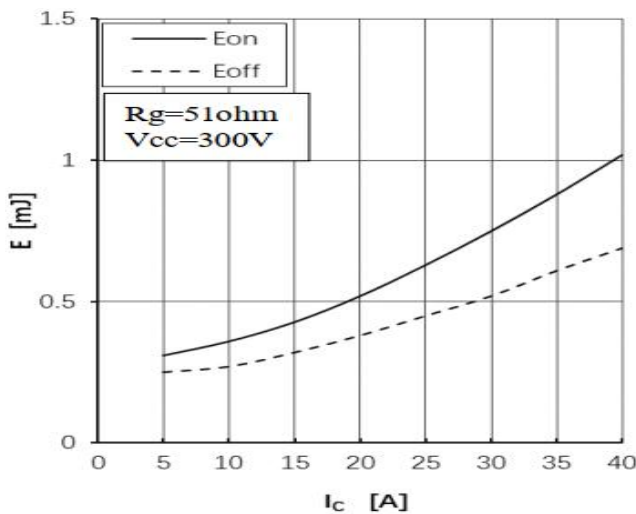


Fig5. IGBT Switching Loss vs. I_c (150°C)

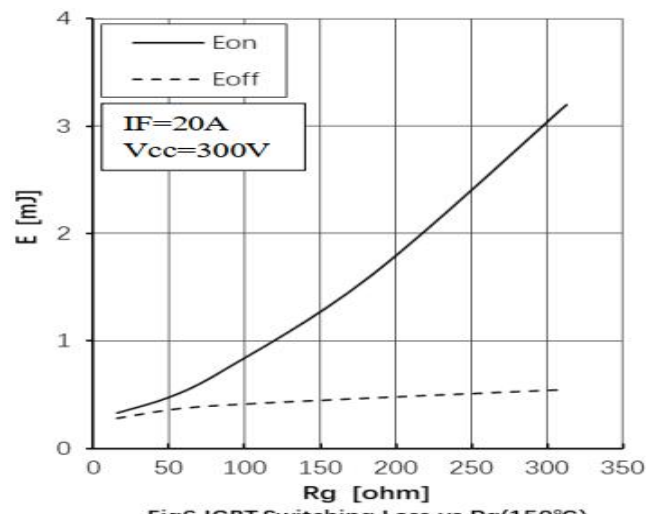


Fig6. IGBT Switching Loss vs. R_g (150°C)

Typical Characteristics

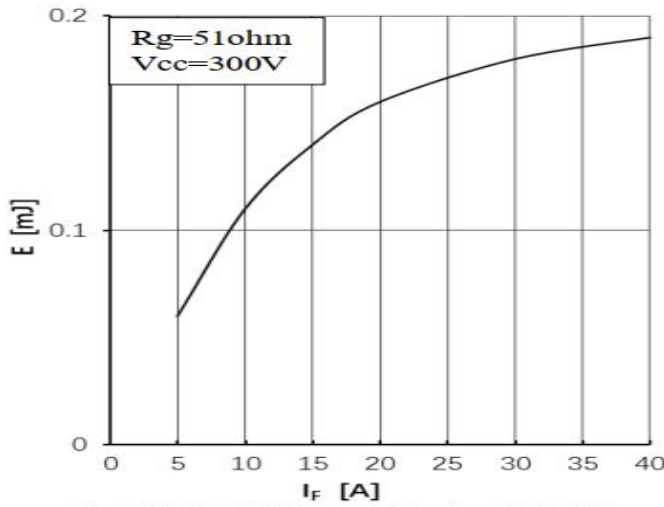


Fig7. Diode Switching Loss(Erec) vs. I_F (150°C)

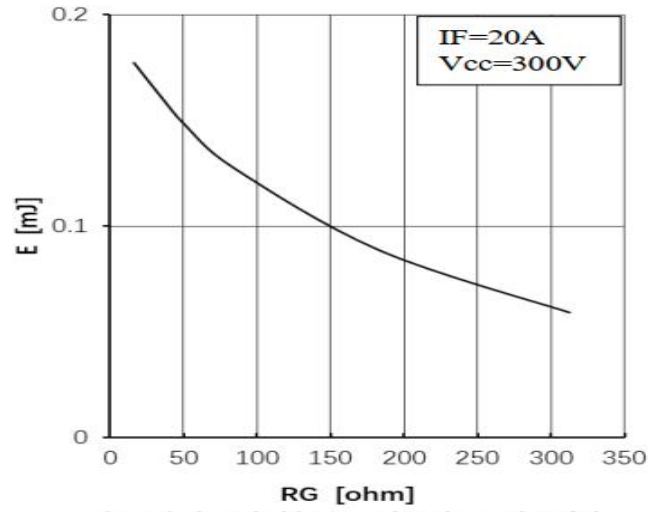


Fig8. Diode Switching Loss(Erec) vs. R_g (150°C)

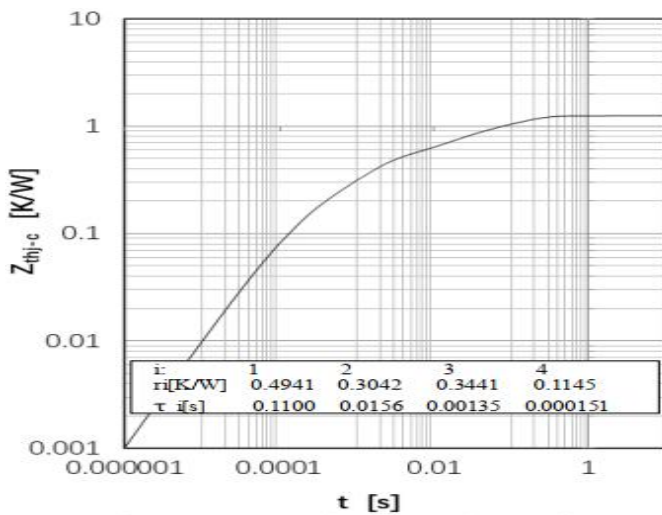


Fig 9. IGBT Transient Thermal Impedance

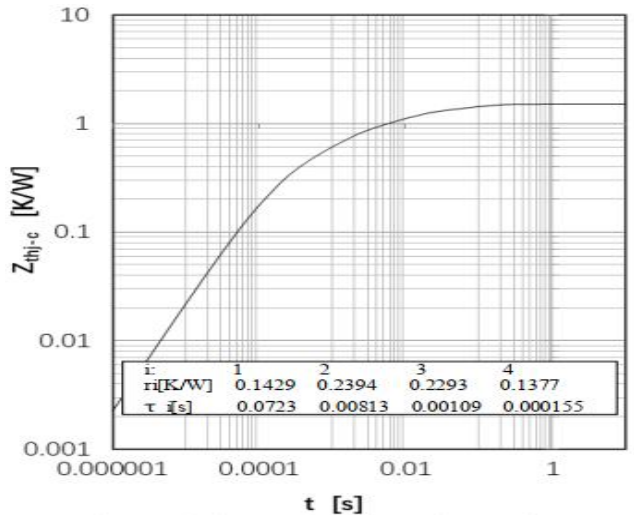
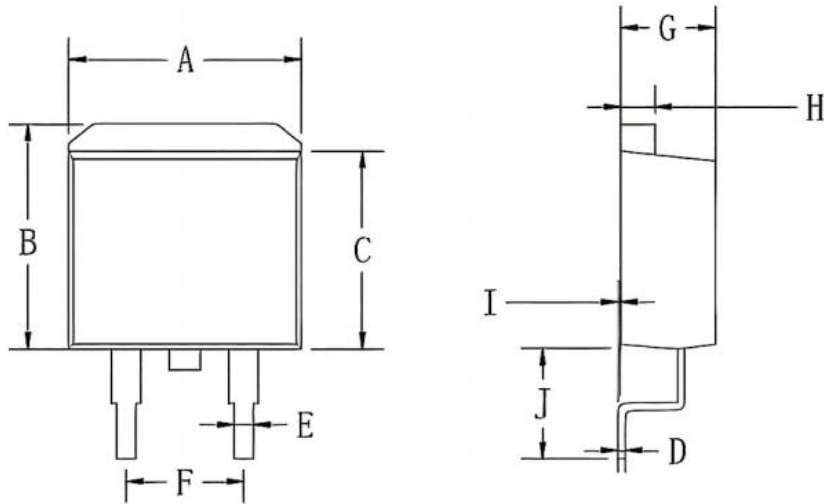


Fig10. Diode Transient Thermal Impedance

TO-263AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.500	11.500	0.374	0.453
B	9.700	10.500	0.382	0.413
C	8.400	9.000	0.331	0.354
D	0.280	0.640	0.011	0.025
E	0.680	0.940	0.027	0.037
F	4.550	5.600	0.179	0.220
G	4.040	5.100	0.159	0.201
H	1.140	1.400	0.045	0.055
I	0.000	0.200	0.000	0.008
J	4.900	6.050	0.193	0.238